

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SENSHO USAMI	03/24/2015
KOJI HOSOKAWA	03/24/2015
RECEIVING PARTY DATA	
Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 S. FEDERAL WAY
Internal Address:	P.O. BOX 6
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15229688
CORRESPONDENCE DATA	
Fax Number:	(206)359-7198
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(206)359-8000
Email:	patentprocurement@perkinscoie.com
Correspondent Name:	PERKINS COIE LLP
Address Line 1:	P.O. BOX 1247
Address Line 2:	PATENT PROCUREMENT
Address Line 4:	SEATTLE, WASHINGTON 98111-1247
ATTORNEY DOCKET NUMBER:	010829-9129.US01
NAME OF SUBMITTER:	JANA BRATTON
SIGNATURE:	/Jana Bratton/
DATE SIGNED:	08/09/2016
Total Attachments: 4	
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ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Sensho Usami, having a mailing address of c/o Micron Akita, Inc., 89-2, Yamada, Yuwaishida, Akita-shi, Akita, 010-1222 Japan; and
- Koji Hosokawa, having a mailing address of c/o Micron Akita, Inc., 89-2, Yamada, Yuwaishida, Akita-shi, Akita, 010-1222 Japan.

The Assignors invented one or more certain inventions (the "Invention(s)") described in (1) an application for patent naming the Assignors as inventors, and filed with the Japan Patent Office on March 31, 2014 as Japan Patent Application No. 2014-072117; and (2) an application for patent naming the Assignors as inventors, titled SEMICONDUCTOR DEVICE INCLUDING SEMICONDUCTOR CHIPS MOUNTED OVER BOTH SURFACES OF SUBSTRATE, and filed with the U.S. Patent and Trademark Office on _____ as U.S. Patent Application No. _____ (the "Applications"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Applications, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in Japan, the United States, and any other countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Applications, and any Patents; any divisional of any of the Applications and any other application claiming priority rights from any of the Applications; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from any of the Applications (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are

unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. This Assignment may be executed in counterparts.

Date: 3/24/15

Sensho Usami
Sensho Usami

Witness:

Shoji Eguchi
Printed Name


Signature

Date: 7/24 '2015

Koji Hosokawa
Koji Hosokawa

Witness:

Shoji Eguchi
Printed Name


Signature